DA3X103E

Silicon epitaxial planar type

For high speed switching circuits 2 elements cathode-common type

■ Features

- ullet Short reverse recovery time t_{rr}
- Low terminal capacitance C_t
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

■ Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25$ °C

| Parameter | | Symbol | Rating | Unit | |
|------------------------------|--------|------------------|-------------|------|--|
| Reverse voltage | | V _R | 80 | V | |
| Maximum peak reverse voltage | | V_{RM} | 80 | V | |
| Forward current | Single | | 100 | mA | |
| | Double | I_{F} | 150 | mA | |
| Peak forward current | Single | | 225 | mA | |
| | Double | I_{FM} | 340 | mA | |
| Non-repetitive peak forward | Single | | 500 | mA | |
| surge current * | Double | I _{FSM} | 750 | mA | |
| Junction temperature | | T _j | 150 | °C | |
| Storage temperature | | T _{stg} | -55 to +150 | °C | |

Note) *: 1 t = 1 s

■ Package

Code

Mini3-G3-B

• Pin Name 1: Anode-1

2: Anode-2

3: Cathode-1 Cathode-2

■ Marking Symbol: 24

■ Internal Connection

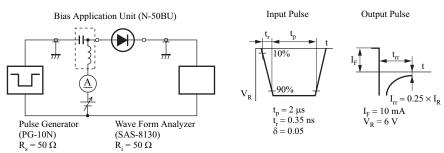


■ Electrical Characteristics $T_a = 25$ °C±3°C

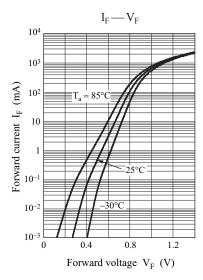
| Parameter | Symbol | Conditions | Min | Тур | Max | Unit |
|-------------------------|-----------------|--|-----|-----|-----|------|
| Forward voltage | V _F | $I_F = 100 \text{ mA}$ | | | 1.2 | V |
| Reverse voltage | V _R | $I_R = 100 \mu A$ | 80 | | | V |
| Reverse current | I_R | $V_R = 80 \text{ V}$ | | | 100 | nA |
| Terminal capacitance | Ct | $V_R = 0 V$, $f = 1 MHz$ | | 2 | 15 | pF |
| Reverse recovery time * | t _{rr} | $I_F = 10 \text{ mA}, V_R = 6 \text{ V}, I_{rr} = 0.25 \times I_R$ | | 2 | 10 | ns |

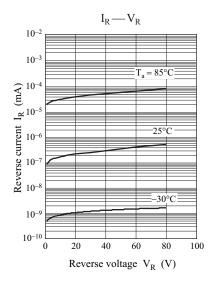
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

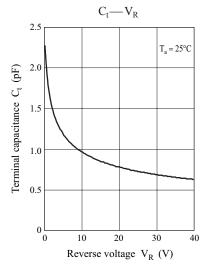
- 2. Absolute frequency of input and output is 100 MHz
- 3. *: t_{rr} measurement circuit



DA3X103E Panasonic

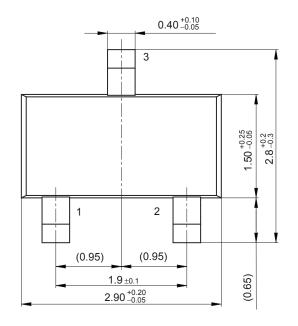


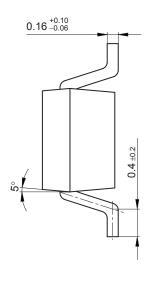




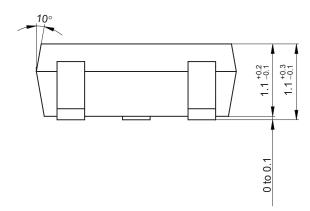
2 Ver. CED

Mini3-G3-B





Unit: mm



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